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(54) Title: PROCESS FOR MAKING A Z-AXIS ADHESIVE AND ESTABLISHING ELECTRICAL INTERCONNECTION THEREWITH

(57) Abstract

A Z-axis adhesive is produced by dispersing electrically-conductive particles in an organic binder and then imagewise exposing the material to electromagnetic radiation, preferably from a laser or a flash lamp, under conditions sufficient to transfer the particles from the binder to a receptor in a patterned fashion such that the resulting adhesive is a Z-axis conductor in the patterned areas. The patterned adhesive can then be used to establish electrical interconnection between facing electrodes of a number of different structures including semiconductor chips and a flexible printed circuit board.